

TRANSISTOR(PNP)

SOT23/TRANS(PNP)/-1500mA/200-350

Rev1.1





SOT23 TRANSISTOR(PNP)

1.Features

- ◆ Complementary to SS8050
- ◆ Power Dissipation of 300mW
- ◆ High Stability and High Reliability

2. Mechanical Data

◆ SOT-23 Small Outline Plastic Package





3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
SS8550	Y2	SOT23	3,000	180,000

4. Maximum Ratings & Thermal Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-40	V
Collector-Emitter Voltage	Vceo	-25	V
Emitter -Base Voltage	V _{EBO}	-5	V
Collector Current-Continuous	lc	-1500	mA
Collector Power Dissipation	Pc	300	mW
Junction Temperature	Tj	150	°C
Storage Temperature	T_{stg}	-55 ~ +150	°C
Thermal resistance From junction to ambient	ReJA	417	°C/W

4.Electrical Characteristics at Ta=25°C

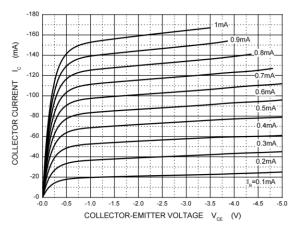
Parameter	Symbol	Test Conditions	Min.	Max.	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =-100uA, I _E =0	-40		V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =-0.1mA, I _B =0	-25		V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =-100uA, I _C =0	-5		V
Collector cut-off current	I _{CEO}	V _{CE} =-20V, I _B =0		-100	nA
Collector cut-off current	Ісво	V _{CB} =-40V, I _E =0		-100	nA
Emitter cut-off current	I _{EBO}	V _{EB} =-5V, I _C =0		-100	nA
DO assessed assista	h _{FE(1)}	V _{CE} =-1V, I _C =-100mA	120	400	
DC current gain	h _{FE(2)}	V _{CE} =-1V, I _C =-800mA	40		
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =-800mA, I _B =-80mA		-0.5	V
Base -emitter saturation voltage	V _{BE(sat)}	I _C =-800mA, I _B =-80mA		-1.2	V
Base-emitter voltage	V_{BE}	V _{CE} =-1V, I _C =-10mA,		-1	V
Transition frequency	f⊤	V _{CE} =-10V, I _C =-50mA, f=30MHz	100		MHz
Collector output capacitance	Cob	V _{CB} =-10V, I _E =0, f=1MHz		20	pF

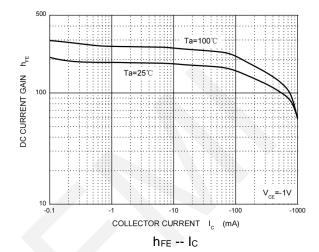


CLASSIFICATION OF hFE(1)

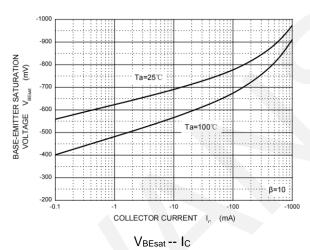
RANK	L	Н	J
RANGE	120-200	200-350	300-400

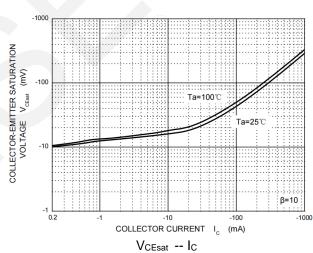
5. Typical Characteristics

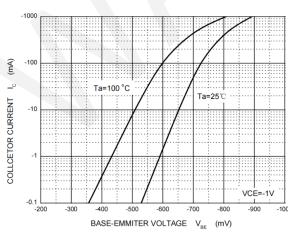


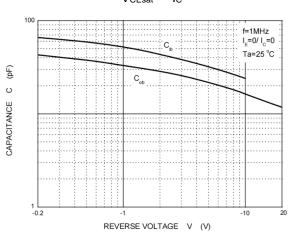


Static Characteristic





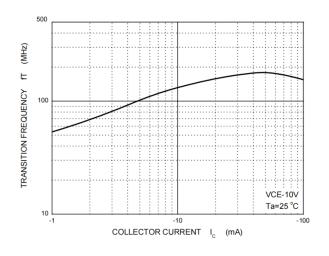


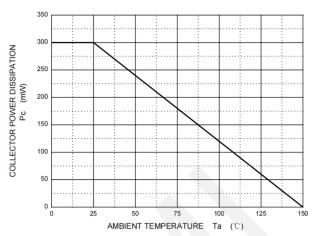


V_{BE} -- I_C

 $C_{ob}/C_{ib} - V_{CB}/V_{EB}$





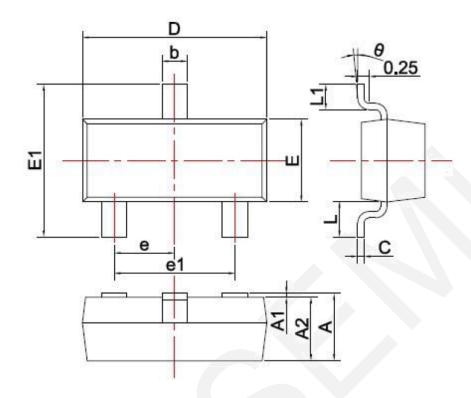


f_T -- I_C

P_C -- T_a



7.Package Dimensions



Symbol	Dimensions in Millimeters			
	MIN.	TYP.	MAX.	
А	0.900		1.150	
A1	0.000		0.100	
A2	0.900		1.050	
b	0.300		0.500	
С	0.080		0.150	
D	2.800		3.000	
E	1.200		1.400	
E1	2.250		2.550	
е		0.950		
e1	1.800		2.000	
L		0.550		
L1	0.300		0.500	
θ	0°		8°	



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